

# LC-2Q252

High-Speed, High-Precision CO2 Laser Drilling Machine  
for HDI/BGA Package PCBs

**The global standard in laser drilling machines**  
**Greater improvements to total productivity through**  
**reduction of non-processing time**

**NEW**  
**PRODUCT**



**Via Mechanics, Ltd.**

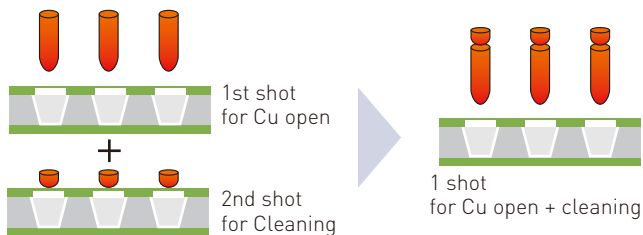
### Improved productivity through the pursuit of better stability and reduction of non-processing time

#### □ Solving HDI PCB small diameter and high precision needs using package processing technologies

Equipped with a high rigidity machine structure and a variety of correction systems to provide the strict precision required for miniaturization and higher density. Also incorporates a variety of proprietary heat countermeasures to achieve more stable drilling precision.

#### □ New technologies which contribute to increased productivity

Introduction of a new laser pulse control method allows for a reduction in the number of shots to achieve both increased productivity and higher quality processing. The development of a new type of power sensor has also made it possible to greatly reduce measurement time (an 80% reduction compared to our previous model), and a new application has made it possible to reduce preparation time by 50%. These reductions in non-processing time contribute to the improvement of total productivity.



Processing speed improved by reducing the number of shots and high quality processing achieved without damaging bottom layers 〈 Patented 〉

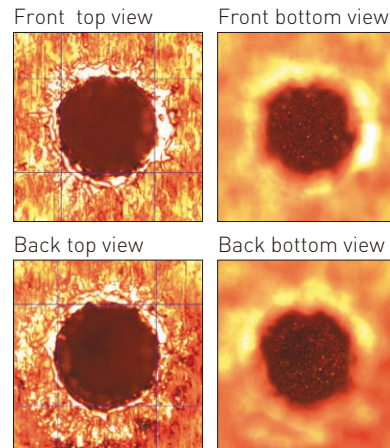
#### □ The industry's top class processing speed

Processing speed has been dramatically improved (a 125% improvement compared to our previous model) by installing our new, in-house designed high-speed galvano scanners in addition to a proprietary XY table and galvano synchronization.

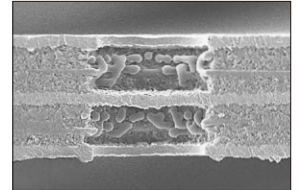
#### LC-2Q252/Major specifications

Max. drilling area	635 x 813mm 2panels
XY positioning speed	50m/min
Number of beams	2
Laser output	500W
Galvano scan area	□70mm (OP : □30mm, □50mm)
Drilling accuracy	±0.010mm
CNC	MARK-55L

#### 3 layer processing

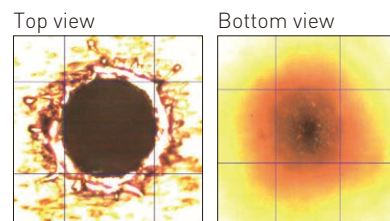


Cross section

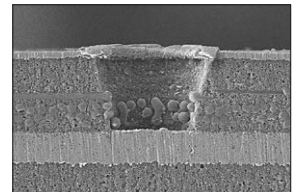


#### Direct drilling of unprocessed Cu

Hole diameter 35  $\mu$ m



Cross section



#### Installation floor plan

